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(54) **Title**: SYSTEM AND METHOD OF PREVENTING PATTERN COLLAPSE USING LOW SURFACE TENSION FLUID

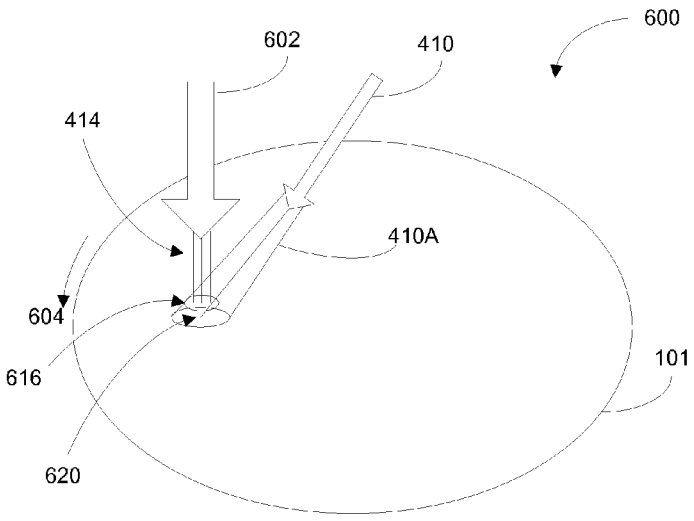


FIG. 6A

(57) **Abstract**: A system for processing a wafer with a low surface tension liquid includes a low surface tension liquid source including a first heat source capable of heating the low surface tension liquid to not more than 25 degrees C less than boiling point of the low surface tension liquid, a delivery mechanism for delivering the heated low surface tension liquid to an air/liquid interface region and a second heat source directed toward the air/liquid interface region, the second heat source capable of heating the air/liquid interface region to at least 2 degrees C greater than the boiling point of the low surface tension liquid. A method for processing a wafer with a low surface tension liquid is also described.

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